

Amendments to the Claims

Claims 1-13. (Cancelled)

14. (New) A tablet machine, which is equipped with a punch and a die for compressing tablets, wherein said punch and die comprise a basis material which is a high-silicon steel.

15. (New) The tablet machine according to claim 14, wherein a surface of the basis material is subjected to a carburization treatment.

16. (New) The tablet machine according to claim 15, wherein the carburization is carried out by contacting the basis material with a gas for carburization containing CO at 400°C to 700°C for 10 to 30 hours.

17. (New) The tablet machine according to claim 14, which is equipped with a punch (4, 6) and a die (3) for compressing tablets containing a corrosive substance or an adhesive substance.

18. (New) The tablet machine according to claim 17, wherein the corrosive substance is an acidic substance.

19. (New) The tablet machine according to claim 17, wherein the adhesive substance is one or more substance(s) selected from the group consisting of an adhesive pharmacologically active substance, an adhesive low-melting substance, and an adhesive excipient.

20. (New) The tablet machine according to claim 19, wherein the adhesive low-melting substance shows a depressed melting point.

21. (New) The tablet machine according to claim 14, wherein the high-silicon steel consists essentially of about 0 to 0.08% by weight C, about 3.5 to 6% by weight Si, about 0 to 5% by weight Mn, about 3 to 9% by weight Ni, about 6 to 15% by weight Cr, and the balance being Fe, the total amount of Ni and Mn being about 2-fold the amount of Si, the amount of Cr being about 2.5-fold the amount of Si, and the transformation temperature for A₃ being not higher than about 750°C.

22. (New) The tablet machine according to claim 14, wherein the high-silicon steel consists essentially of about 0 to 0.05% by weight C, about 3.5 to 6% by weight Si, about 2 to 6% by weight Mn, about 1 to 4% by weight Ni, about 8 to 16% by weight Cr, about 0.3 to 3% by weight Mo, about 1 to 4% by weight Cu, and the balance being Fe, the total amount of Ni, Mn and Cu being about 2.5-fold the amount of Si, the amount of Cr being about 3-fold the amount of Si, and the transformation temperature for A₃ being not higher than about 750°C.

23. (New) The tablet machine according to claim 14, wherein the high-silicon steel consists essentially of about 0 to 0.1% by weight C, about 4 to 9% by weight Si, about 0 to 3% by weight Mn, about 6 to 18% by weight Ni, about 16 to 25% by weight Cr, about 0 to 3% by weight Mo, about 0 to 3% by weight Co and/or about 0 to 2% by weight Cu, and the balance being Fe, the total amount of Ni and Mn being about 2-fold the amount of Si, the amount of Cr being about 3.5-fold the amount of Si, and the transformation temperature for A₃ being not higher than about 750°C.

24. (New) The tablet machine according to claim 14, wherein the high-silicon steel consists essentially of about 0 to 0.05% by weight C, about 4 to 7% by weight Si, about 0 to 3% by weight Mn, about 6 to 16% by weight Ni, about 12 to 20% by weight Cr, about 0 to 4% by weight V, about 0 to 4% by weight Mo, about 0 to 4% by weight W, about 0 to 1% by weight Ti, about 0 to 1% by weight Al and/or about 0 to 1% by weight Co, about 0 to 1% by weight Cu, and the balance being Fe, the total amount of Ni and Mn being about 2-fold the amount of Si, the

amount of Cr being about 3.5-fold the amount of Si, and the transformation temperature for A₃ being not higher than about 750°C.

25. (New) The tablet machine according to claim 14, wherein the high-silicon steel consists essentially of about 0 to 0.05% by weight C, about 2 to 4% by weight Si, about 0 to 2% by weight Mn, about 5 to 10% by weight Ni, about 8 to 13% by weight Cr, about 0.2 to 1% by weight Mo, about 0.5 to 3% by weight Cu, and the balance being Fe, the sum of the 2 times amount of Cr and the amount of Si being about 20-30% by weight of the whole amount.

26. (New) A method for manufacturing tablets, which comprises compressing granules disposed in the punch and die of the tablet machine according to claim 14 into tablets.

27. (New) The method according to claim 26, wherein the tablets contain a corrosive substance or an adhesive substance.

28. (New) The method according to claim 27, wherein the corrosive substance is an acidic substance.

29. (New) The method according to claim 27, wherein the adhesive substance is one or more substance(s) selected from a group consisting of an adhesive pharmacologically active substance, an adhesive low-melting substance and an adhesive excipient.

30. (New) The method according to claim 29, wherein the adhesive low-melting substance shows a depressed melting point.

31. (New) Tablets which are manufactured according to the method of claim 26.